

METHOD FOR MAKING SUPPORT STRUCTURE FOR PROBING DEVICE

ABSTRACT

A method for making a support structure for a probing device includes a step
5 of providing a substrate having first internal conductive lines, a carrier having second
internal conductive lines and a thickness less than 2 mm for packaging an integrated
circuit chip, solder balls, and photoresist support blocks made by lithography in a way
that the solder balls and the photoresist support blocks are disposed between the
substrate and the carrier, the photoresist support blocks separately arranged from each
10 other, and at least one of the photoresist support blocks is disposed between two
adjacent solder balls. The method further includes a step of electrically connecting the
first internal conductive lines with the second internal conductive lines respectively by
soldering the carrier and the substrate with the solder balls by reflow soldering.

15 FIGURE 4